

# 4R3TI60Y-080

## DIODE & THYRISTOR MODULE

800V / 60A

DIODE & THYRISTOR MODULE

### ■ Features

- Glass Passivation Chip
- Easy Connection
- Insulated Type
- Large di/dt
- Large dv/dt

### ■ Applications

- Inverters
- Battery Chargers
- DC Motors
- General Purpose DC Power Supplies

### ■ Maximum ratings and characteristics

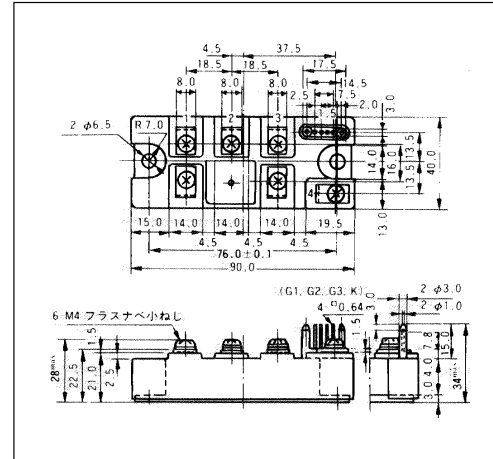
#### ● Absolute maximum ratings

Item	Symbol	Conditions	Rating	Unit	
Repetitive peak reverse voltage	$V_{RRM}$		800	V	
Repetitive peak off voltage	$V_{DRM}$		800	V	
Non-repetitive peak reverse voltage	$V_{RSM}$		900	V	
Average output current	$I_O$	50/60Hz Sine wave, $T_c=87^\circ\text{C}$	60	A	
Surge current	$I_{FSM}$	From rated load, Sine wave 8.3ms	1000	A	
$I^2t$	$I^2t$	From rated load, 8.3ms	4150	$\text{A}^2\text{s}$	
Operating junction temperature	$T_j$		-40 to +125	$^\circ\text{C}$	
Storage temperature	$T_{stg}$		-40 to +125	$^\circ\text{C}$	
Isolation voltage	$V_{is}$	AC 1min.	2000	V	
Screw torque	Moumting	M5	3.0 *1	N·m	
	Terminals	M4	1.7 *2	N·m	
Thyristor	di/dt	$T_j=125^\circ\text{C}$ , $f=50\text{Hz}$ , $V_D=1/2V_{DRM}$ $I_{TM}=120\text{A}$ , $I_{GM}=0.3\text{A}$ , $di_g/dt=0.3\text{A}/\mu\text{s}$	100	$\text{A}/\mu\text{s}$	
	Forward peak gate current	$I_{FGM}$	100 $\mu\text{s}$ max	A	
	Peak gate power	$P_{GM}$	100 $\mu\text{s}$ max	W	
	Average gate power	$P_{G(AV)}$		0.5	W
	Peak reverse gate voltage	$V_{RGM}$		5	V

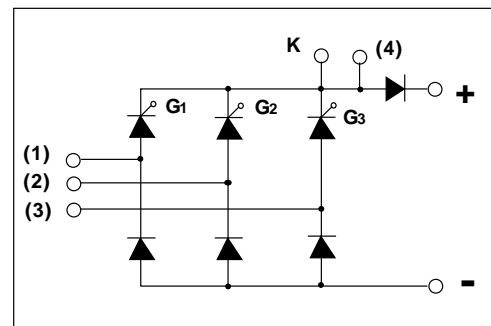
\*1: Recommendable value : 2.0 to 3.0 N·m(M5)

\*2: Recommendable value : 1.3 to 1.7 N·m(M4)

### ■ Outline Drawings, mm



### ■ Inner Circuit Schematic



●Electrical characteristics (Ta=25°C Unless otherwise specified)

Item		Symbol	Conditions	Min.	Typ.	Max.	Unit
Thyristor	Forward voltage drop	V <sub>FM</sub>	T <sub>j</sub> =25°C, I <sub>FM</sub> =60A			1.30	V
	Reverse current	I <sub>RRM</sub>	T <sub>j</sub> =125°C, V <sub>R</sub> =V <sub>RRM</sub>			6	mA
	Off current	I <sub>DRM</sub>	T <sub>j</sub> =125°C, V <sub>R</sub> =V <sub>DRM</sub>			6	mA
	Gate trigger current	I <sub>GT</sub>	T <sub>j</sub> =25°C, V <sub>D</sub> =6V I <sub>T</sub> =1A			80	mA
	Gate trigger voltage	V <sub>GT</sub>				2.5	V
	Gate non-trigger voltage	V <sub>GD</sub>	T <sub>j</sub> =125°C, V <sub>D</sub> =1/2V <sub>DRM</sub>	0.2			V
		I <sub>H</sub>				200	mA
		dv/dt	T <sub>j</sub> =125°C, V <sub>D</sub> =2/3V <sub>DRM</sub>	500			V/μs
	Turn-on time	t <sub>gt</sub>	T <sub>j</sub> =25°C, V <sub>D</sub> =1/2V <sub>DRM</sub> I <sub>TM</sub> =120A I <sub>GM</sub> =0.3A diG/dt=0.3A/μs		3		μs
	Turn-off time	T <sub>q</sub>	T <sub>j</sub> =125°C, I <sub>TM</sub> =60A -di/dt=5A/μs V <sub>R</sub> =>50v V <sub>D</sub> =1/2V <sub>DRM</sub>		150		μs
Diode	Forward voltage drop	V <sub>FM</sub>	T <sub>j</sub> =25°C, I <sub>FM</sub> =60A	Rectifier diode		1.20	V
				Output diode		1.10	V
	Reverse current	I <sub>RRM</sub>	T <sub>j</sub> =125°C, V <sub>R</sub> =V <sub>RRM</sub>	Rectifier diode		5	mA
				Output diode		10	mA

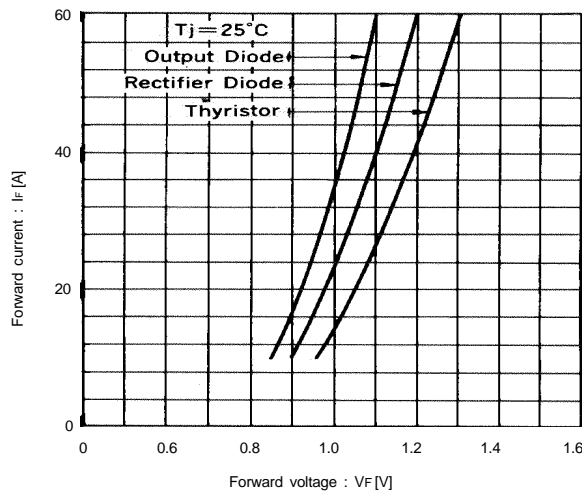
● Thermal Characteristics

Item	Symbol	Conditions	Min.	Typ.	Max.	Unit
Thermal resistance	R <sub>th(j-c)</sub>	Junction to case 1 Chip	Thyristor		1.5	°C/W
			Rectifier diode		1.6	
			Output diode		0.6	
	R <sub>th(c-f)</sub>	the base to cooling fin *			0.06	°C/W

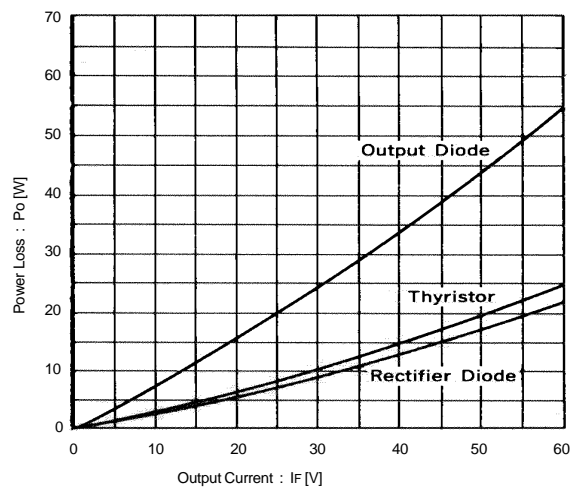
\* : With Thermal Compound

■ Characteristics

Maximum On-State Voltage/Forward Voltage Characteristics (Per 1 chip)

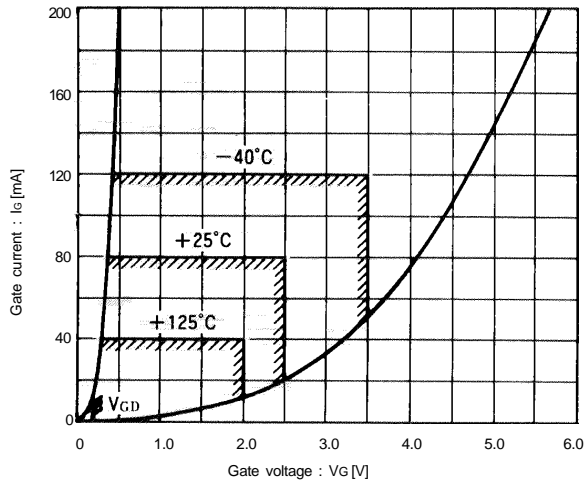


Output Current vs. Power Loss (Per 1 chip)

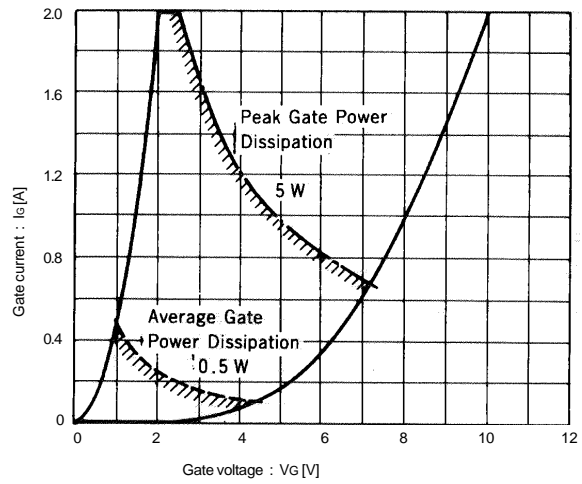


Characteristics

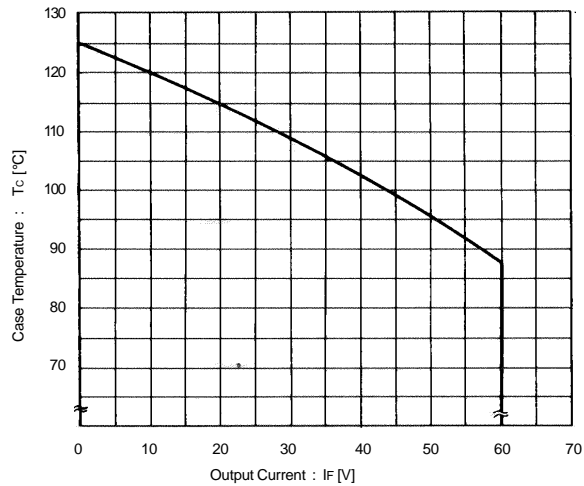
Gate Characteristics



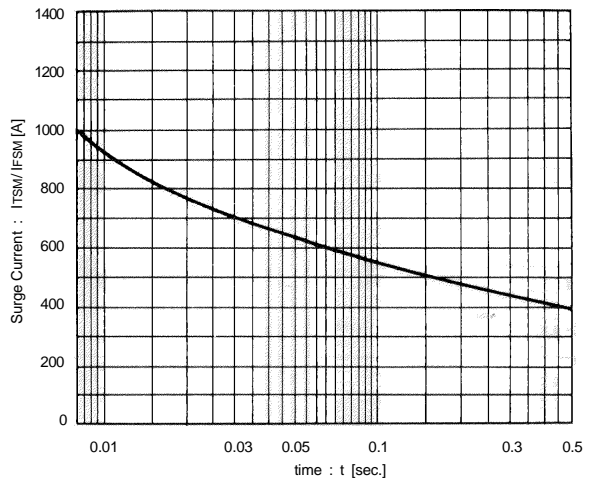
Gate Characteristics



Output Current vs. Case Temperature



Surge Current



Transient Thermal Impedance  
(Per 1 chip, Junction to Case)

